IN THE CLAIMS:

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1.	(Original)	A multilayer	board,	, comprising
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a signal line requiring tamper-resistance, the signal line including: (a) a conductive trace and (b) a conductive via that passes through layers of the multilayer board, wherein

the conductive trace and an end of the conductive via existing on an outside layer of the multilayer board are placed under one or more circuit components mounted on the outside layer.

- 2. (Original) The multilayer board of Claim 1, wherein
- the signal line further includes a conductive trace on an inner layer that is sandwiched between sheets of foil and/or circuit components placed on layers above and below the inner layer so that the sheets of foil and/or circuit components hide the conductive trace on the inner layer when viewed from above or below.
- 3. (Original) The multilayer board of Claim 2, wherein the sheets of foil placed on the layers that are outside the inner layer are connected to either a ground or a power source.
- 4. (Original) The multilayer board of Claim 3, wherein
 the conductive trace on the outside layer is further covered by a circuit component
 on another outside layer when viewed from above or below.

1	5.	(Original) The multilayer board of Claim 2, wherein
2		the signal line requiring tamper-resistance is either a signal line that is input to an
3	encryption ur	nit or a signal line that is output from a decryption unit.
1	6.	(Original) A multilayer board, comprising:
2		a certain signal line that includes (a) a conductive trace and (b) a conductive via
3	that passes th	rough layers of the multilayer board, wherein
4		the conductive trace and an end of the conductive via existing on an outside layer
5	of the multila	ayer board are placed under one or more circuit components mounted on the outside
6	layer,	•
· 7		the certain signal line further includes a conductive trace on an inner layer that is
8	sandwiched l	between sheets of foil and/ or circuit components placed on layers above and below
9	the inner lay	er so that the sheets of foil and/or circuit components hide the conductive trace on
10	the inner laye	er when viewed from above or below, and
11		the certain signal line is either a data line or an address line.
1	7-29.	(Cancelled)
1	30.	(New) A tamper-resistant multilayer board for transfer of pixel data to be
2	encrypted co	mprising:
3		a board member having a plurality of layers and one or more components
4	mounted the	reon;
5		a reception/decryption unit mounted on the board member;

an output interface unit mounted on the board member and operatively connected	d
to the reception/decryption unit; and	

a conductive path operatively designed for interconnecting the reception/
decryption unit and the output interface unit and position adjacent an interior layer surface for a
portion of the conductive path and positioned under one or more components for the remainder
of the conductive path to prevent direct access from the exterior of the board member.